SURAGUS
Sensors & Instruments

EddyCus® map C2C – Automated Resistivity Imaging Device

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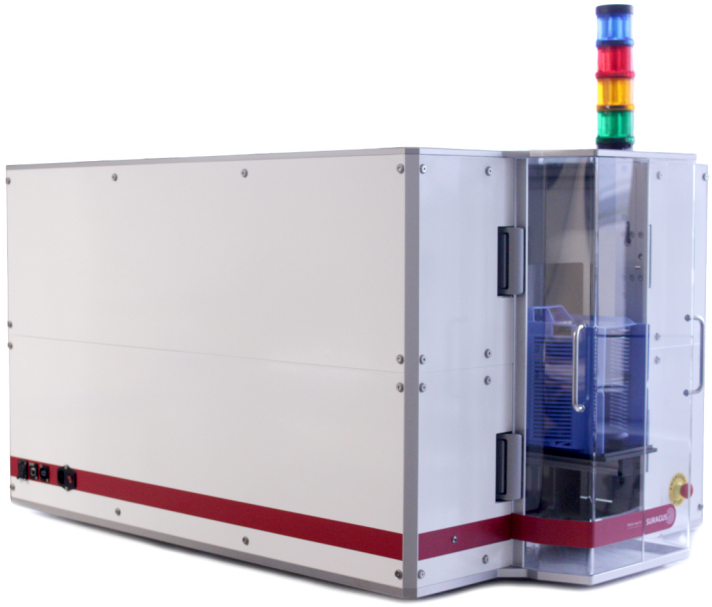

Highlights

- Contact-free
- Automated wafer handling
- Fast (one measurement within 60 seconds)
- High resolution (5 to 22,000) points
- Repeatable and accurate
- Customized setups
- Without edge grip

Parameters

- Resistivity (mOhm·cm)
- Sheet resistance (Ohm/sq)
- Metal layer thickness (nm, µm)
- Total thickness varation (µm)
- Defect and integrity assessment

Applications

- Boule, puck and wafer characterization
- Layer deposition (PVD, CVD, plating …)
- Epitaxy
- Implantation
- Doping
- Annealing
- Laser irradiation
- Etching
- Machining and Polishing
- Wafer sorting
- (De)-oxidation
- Defect imaging
- Final inspection

Materials

- Semiconductors
  - Si
  - SiC
  - GaAs
  - GaN
- Metal films
  - Al
  - Au
  - Ti
  - Cu
- Other conductive films and materials

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Visit us at:
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www.suragus.com/calculator
www.suragus.com/EddyCusMapC2C

Engineered and Made in Germany

TÜV SÜD ISO 9001

JEC GROUP WINNER OF 2016 INNOVATION AWARD

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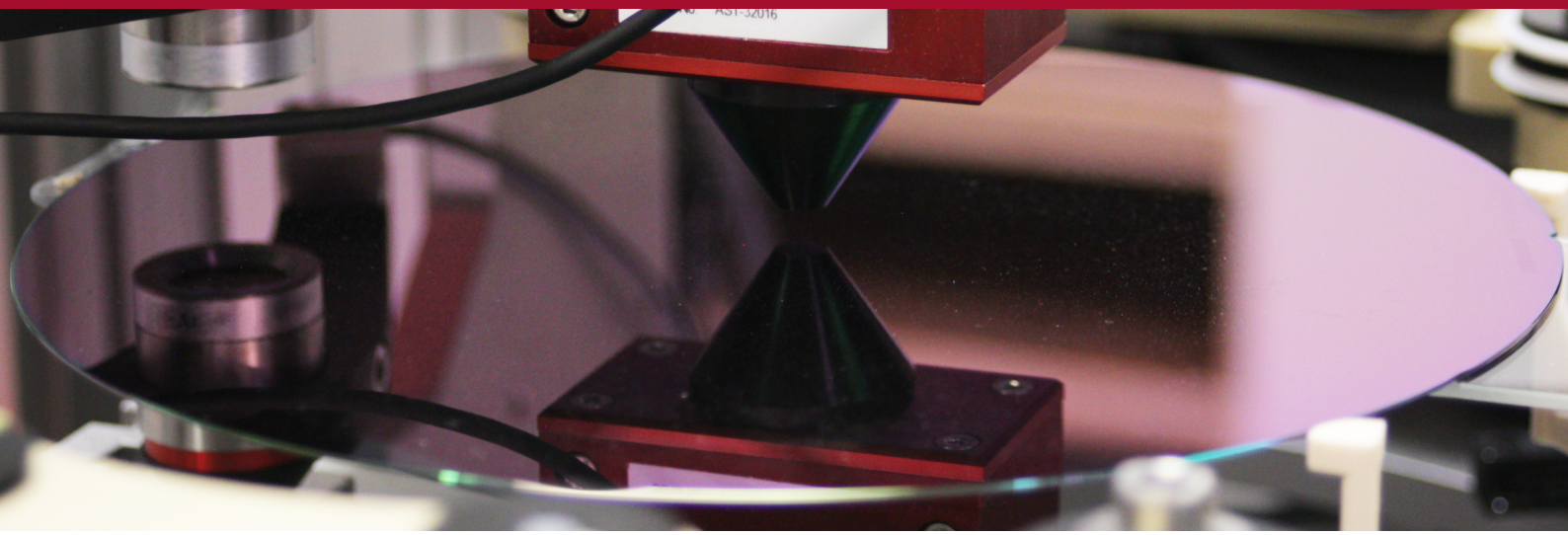

Measurement technology	Non-contact high frequency eddy current sensor, Confocal sensor for TTV
Substrates	6 / 8 inch wafer
Wafer thickness range	300 – 1,300 µm (other on request)
Cassettes	1
Edge effect correction / exclusion	2 – 10 mm (depending on size, range, setup and requirements)
Resistivity range	0.1 – 1,000 mOhm·cm < 1 – 3 % accuracy
Thickness measurement of metal films (e.g. Aluminum, Copper)	2 nm – 2 mm (in accordance with sheet resistance)
Measurement patterns	Standard ~ 22 000 points Points 9 / 17 / 49 / 81 / 99 / 169 / 625 / …. / 100,000
Measurement time	30 – 90 s per wafer depending on measurement points
Rotation speed	2 Hz
Throughput	45 wafers per hour (~ 22 000 measurement points per wafer)
Device dimensions (w/d/h)	785 mm x 1,170 mm x 666 mm / 30.91“ x 46.06“ x 26.22“
Available features	Sheet resistance, metal thickness, TTV, Carrier ID reader

Software and Handling

- Web Interface
- Easy to use software
- Recipe Management to adjust thresholds, data processing pipelines, result export options and more
- Display of mapping with intuitive graphical analysis tools
- Access Level for user profiles
- Extensive Job Management
  - Creation of default jobs for 150 and 200mm
  - Freely customizable sequence Jobs
  - Single Wafer analysis
- Result download via Webpage / API / FTP (future) / SECS-GEM (extrem future)
- Creation of statistics for mappings and thickness measurements